



APPENDIX

Changes to Claims:

Claim 35 is canceled.

Claims 25 and 34 are amended.

The following are marked-up versions of the amended claims:

25. (Three Times Amended) A semiconductor device, comprising:

a semiconductor chip having a plurality of pads; and

a flexible substrate having an opening formed therein, the flexible substrate having a common lead having an electrical connection branch connected to one of the pads without support by the flexible substrate, the common lead having a middle portion, the middle portion extending from two edges of the opening and continuously being positioned inside the opening without connection to the pads, and end portions of the common lead being formed on the flexible substrate.

34. (Three Times Amended) A semiconductor chip, comprising:

a plurality of pads for signal arranged in at least one first line;

a plurality of pads for power source arranged in at least one second line different from the at least one first line; and

a plurality of pads for grounding,

wherein all of the pads for signal are disposed in areas closer to edges of the semiconductor chip than all of the pads for power source and grounding.

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